

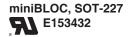
# GigaMOS™ Power MOSFET

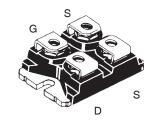
# IXFN230N20T

N-Channel Enhancement Mode Avalanche Rated Fast Intrinsic Diode



 $V_{DSS} = 200V$   $I_{D25} = 220A$   $R_{DS(on)} \le 7.5m\Omega$   $t_{rr} \le 200ns$ 





G = Gate	D = Drain
S - Source	

Either Source Terminal S can be used as the Source Terminal or the Kelvin Source ( Gate Return ) Terminal.

### **Features**

- International Standard Package
- miniBLOC, with Aluminium Nitride Isolation
- Isolation voltage 2500 V~
- High Current Handling Capability
- Fast Intrinsic Diode
- Avalanche Rated
- Low R<sub>DS(on)</sub>

#### **Advantages**

- Easy to Mount
- Space Savings
- High Power Density

### **Applications**

- Synchronous Recification
- DC-DC Converters
- Battery Chargers
- Switched-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC Motor Drives
- Uninterruptible Power Supplies
- High Speed Power Switching Applications

Symbol	Test Conditions	Maximum	Maximum Ratings		
V <sub>DSS</sub>	$T_J = 25^{\circ}C$ to $175^{\circ}C$	200	V		
V <sub>DGR</sub>	$T_J = 25^{\circ}C$ to 175°C, $R_{gs} = 1M\Omega$	200	V		
V <sub>GSS</sub>	Continuous	±20	V		
V <sub>GSM</sub>	Transient	±30	V		
I <sub>D25</sub>	T <sub>c</sub> = 25°C ( Chip Capability)	220	A		
I <sub>L(RMS)</sub>	External Lead Current Limit	200	Α		
I <sub>DM</sub>	$\rm T_{_{\rm C}}$ = 25°C, Pulse Width Limited by $\rm T_{_{\rm JM}}$	630	Α		
I <sub>A</sub>	T <sub>c</sub> = 25°C	100	A		
E <sub>AS</sub>	$T_{c} = 25^{\circ}C$	5	J		
dv/dt	$I_{S} \le I_{DM}, V_{DD} \le V_{DSS}, T_{J} \le 175^{\circ}C$	20	V/ns		
P <sub>D</sub>	T <sub>c</sub> = 25°C	1090	W		
T <sub>J</sub>		-55 +175	°C		
T <sub>.IM</sub>		175	°C		
T <sub>stg</sub>		-55 +175	°C		
V <sub>ISOL</sub>	50/60 Hz, RMS t = 1 minute	2500	V~		
	$I_{ISOL} \le 1 \text{mA}$ $t = 1 \text{ second}$	3000	V~		
M <sub>d</sub>	Mounting Torque	1.5/13	Nm/lb.in		
-	Terminal Connection Torque	1.3/11.5	Nm/lb.in		
Weight		30	g		

		cteristic Typ.	Values Max.		
BV <sub>DSS</sub>	$V_{GS} = 0V, I_{D} = 3mA$	200			V
V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 8mA$	3.0		5.0	V
I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$			±200	nA
I <sub>DSS</sub>	$V_{DS} = V_{DSS}, V_{GS} = 0V$			50	μΑ
	$T_J = 15$	0°C		3	mA
R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 60A, Note 1$			7.5	mΩ



Symbol	bol Test Conditions Characteristic Valu		c Values	
$T_J = 25^{\circ}C$	Unless Otherwise Specified)	Min.	Тур.	Max.
g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 60A, Note 1$	90	150	S
C <sub>iss</sub>			24	nF
C <sub>oss</sub>	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		2440	pF
C <sub>rss</sub>			60	pF
$R_{Gi}$	Gate Input Resistance		1.15	Ω
t <sub>d(on)</sub>	$\begin{cases} & \textbf{Resistive Switching Times} \\ & \textbf{V}_{GS} = 10 \textbf{V}, \ \textbf{V}_{DS} = 0.5 \bullet \textbf{V}_{DSS}, \ \textbf{I}_{D} = \textbf{I}_{D} = 0.5 \bullet \\ & \textbf{R}_{G} = 1 \Omega \ (\text{External}) \end{cases}$		58	ns
t, \		05•1	38	ns
t <sub>d(off)</sub>		D25	62	ns
t,			17	ns
$Q_{g(on)}$			358	nC
Q <sub>gs</sub>	$ V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25} $	•   <sub>D25</sub>	138	nC
$\mathbf{Q}_{gd}$			60	nC
R <sub>thJC</sub>				0.138 °C/W
R <sub>thCS</sub>			0.15	°C/W

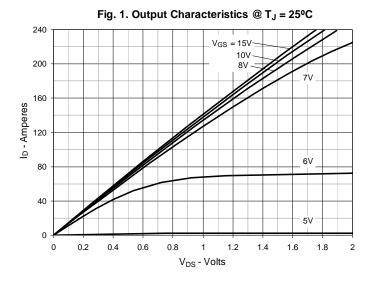
## SOT-227B (IXFN) Outline (M4 screws (4x) supplied) MILLIMETERS MYZ MAX 1.255 .323 MIN 31.50 7.80 4.09 4.09 MAX 31.88 8.20 4.29 .161 .161 .169 .169 4.29 .161 30.12 38.00 11.68 .481 .378 .033 .506 1.001 .460 12.22 9.60 0.84 25.42 2.13 5.97 26.90 4.42 4.85 25.07 .078 .084 .195 1.045 -.002 .004 -0.05 0.1

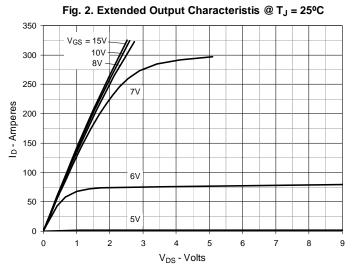
#### Source-Drain Diode

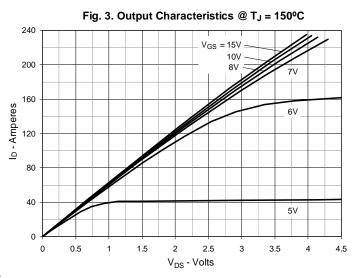
SymbolTest ConditionsCharacteristics $(T_J = 25^{\circ}C, Unless Otherwise Specified)$ Min.		cteristic Values Typ.   Max.			
Is	$V_{GS} = 0V$			230	Α
I <sub>sm</sub>	Repetitive, Pulse Width Limited by $\mathrm{T}_{_{\mathrm{JM}}}$			920	Α
V <sub>SD</sub>	$I_F = 60A, V_{GS} = 0V, \text{ Note 1}$			1.3	V
t <sub>rr</sub> Q <sub>RM</sub>	$I_F = 115A$ , $V_{GS} = 0V$ -di/dt = $100A/\mu s$ $V_R = 75V$		0.74 10.6	200	ns µC A

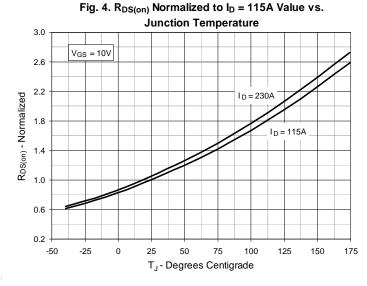
Note 1: Pulse test,  $t \le 300 \mu s$ , duty cycle,  $d \le 2\%$ .

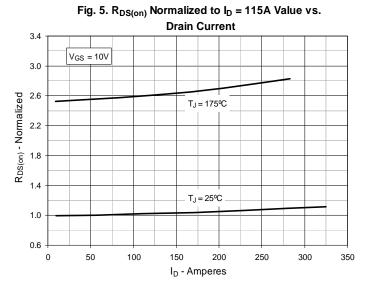


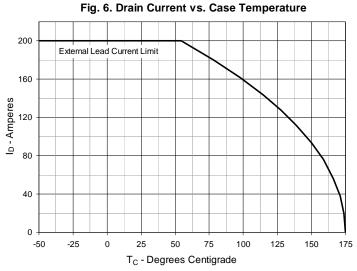






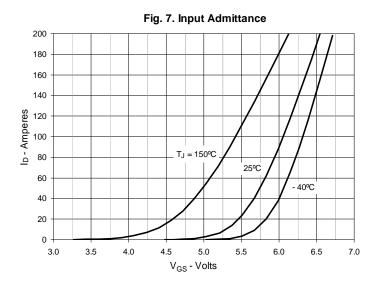


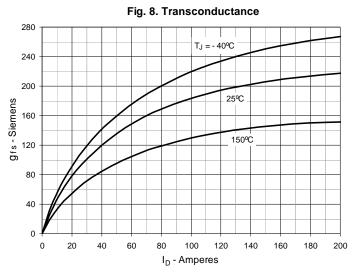


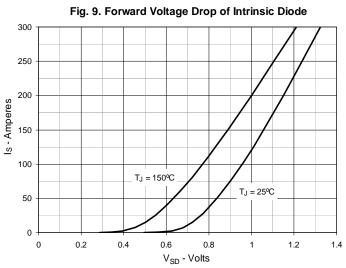


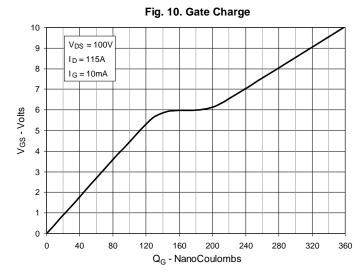
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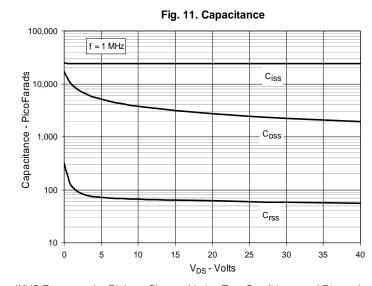


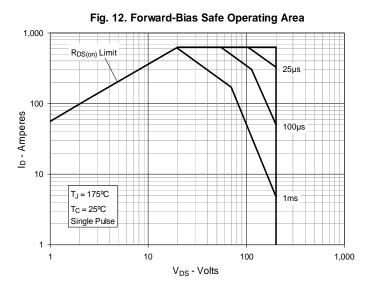












 $\ensuremath{\mathsf{IXYS}}$  Reserves the Right to Change Limits, Test Conditions, and Dimensions.



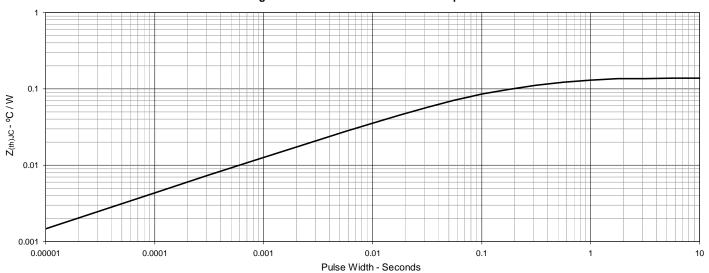


Fig. 19. Maximum Transient Thermal Impedance

